MR810 thru MR814
MR816 thru MR818

MOTOROLA

Designers Data Sheet

SUBMINIATURE SIZE, AXIAL LEAD MOUNTED FAST RECOVERY POWER RECTIFIERS

. . . designed for special applications such as dc power supplies, inverters, converters, ultrasonic systems, choppers, low RF interference and free-wheeling diodes. A complete line of fast recovery rectifiers having typical recovery time of 350 nanoseconds providing high efficiency at frequencies to 100 kHz.

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DESIGNER'S DATA FOR "WORST CASE" CONDITIONS

The Designers Data Sheet permits the design of most circuits entirely from the information presented. Limit curves — representing device characteristic boundaries — are given to facilitate "worst case" design.

MAXIMUM RATINGS

Rating	Symbol	MR810	MR811	MR812	MR813	MR814	MR816	MR817	MR818	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	100	200	300	400	600	800	1000	Volts
Non-Repetitive Peak Reverse Voltage	V_{RSM}	100	200	300	400	500	800	1000	1200	Volts
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	210	280	420	560	700	Volts
Average Rectified Forward Current (Single phase, resistive load, $T_A = 75^oC$)	I_O	←				1.0			→	Amp
Non-Repetitive Peak Surge Current (surge applied at rated load conditions) ($T_A = 75^oC$)	I_{FSM}	←				30			→	Amps
Operating Junction Temperature Range	T_J	←				-65 to +150			→	^oC
Storage Temperature Range	T_{stg}	←				-65 to +175			→	^oC

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient (Typical Primted Circuit Board Mounting)	$R_{\theta JA}$	65	$^oC/W$

ELECTRICAL CHARACTERISTICS

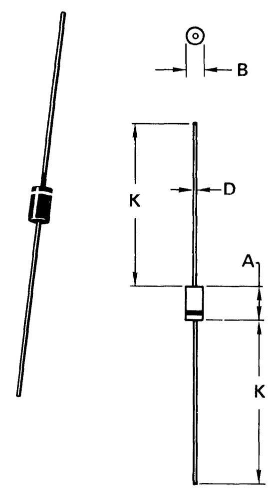
Characteristic	Symbol	Min	Typ	Max	Unit
Instantaneous Forward Voltage ($i_F = 3.14$ Amp, $T_J = 150^oC$)	v_F	–	1.1	1.2	Volts
Forward Voltage ($I_F = 1.0$ Amp, $T_A = 25^oC$)	V_F	–	1.0	1.2	Volts
Reverse Current (rated dc voltage) $T_A = 25^oC$ $T_A = 100^oC$	I_R	– –	1.0 50	10 100	µA

REVERSE RECOVERY CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Recovery Time ($I_F = 1.0$ Amp to $V_R = 30$ Vdc) (Figure 21) ($I_F = 20$ mA, $I_R = 2.0$ mA, Tektronix S-Plug-In) (Figure 22)	t_{rr}	– –	350 1.5	750 3.0	ns µs
Reverse Recovery Current ($I_F = 1.0$ Amp to $V_R = 30$ Vdc) (Figure 21)	$I_{RM(REC)}$	–	–	3.0	Amp

FAST RECOVERY POWER RECTIFIERS

50-1000 VOLTS
1 AMPERE



	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	5.97	6.60	0.235	0.260
B	2.79	3.05	0.110	0.120
D	0.76	0.86	0.030	0.034
K	27.94	–	1.100	–

CASE 59-04

MECHANICAL CHARACTERISTICS

CASE: Transfer Molded Plastic

FINISH: External leads are plated and are readily solderable

POLARITY: Cathode indicated by Polarity band

WEIGHT: 0.4 Grams (Approximately)

FIGURE 1 — FORWARD VOLTAGE

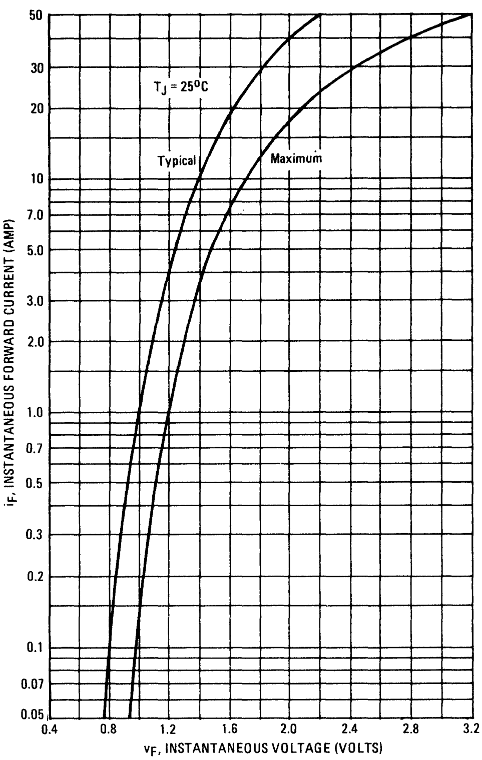


FIGURE 2 — MAXIMUM SURGE CAPABILITY

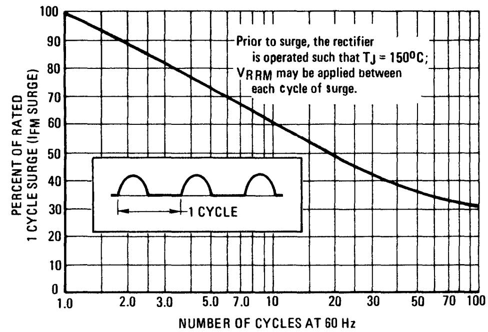


FIGURE 3 — TEMPERATURE COEFFICIENT

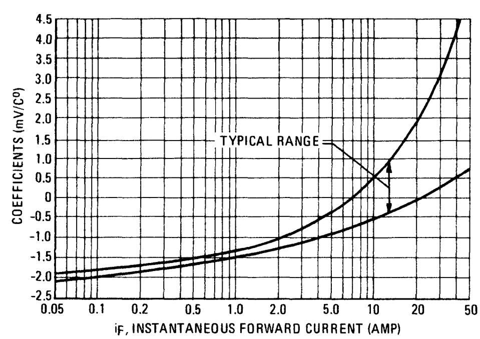


FIGURE 4 — FORWARD POWER DISSIPATION

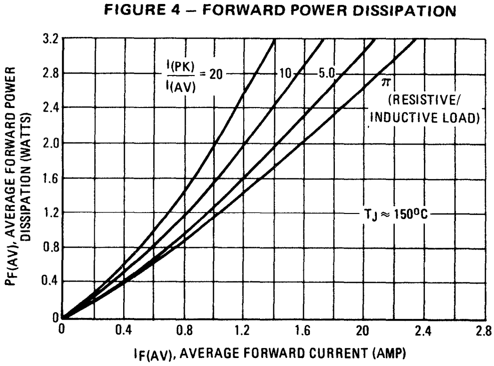
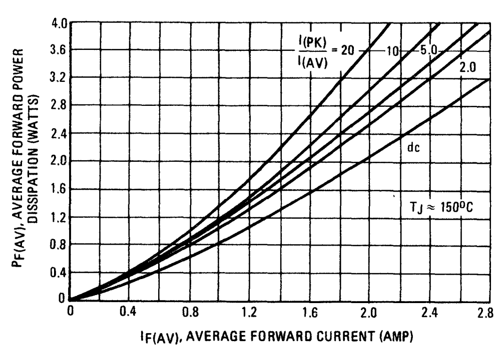


FIGURE 5 — FORWARD POWER DISSIPATION



MAXIMUM CURRENT RATINGS
(SEE NOTES 1 and 2)

SINE WAVE INPUT

FIGURE 6 — EFFECT OF LEAD LENGTHS, RESISTIVE LOAD

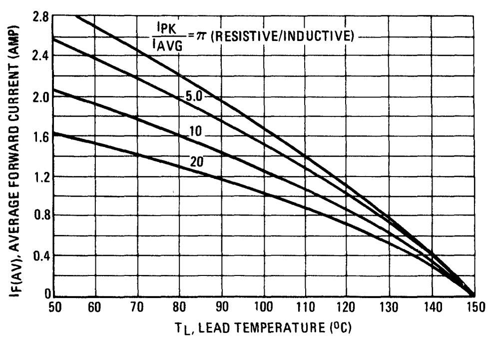


FIGURE 8 — 1/8" LEAD LENGTH, VARIOUS LOADS

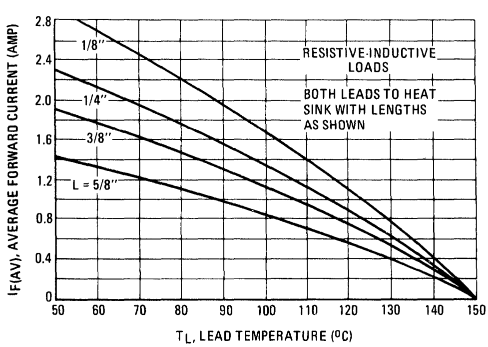
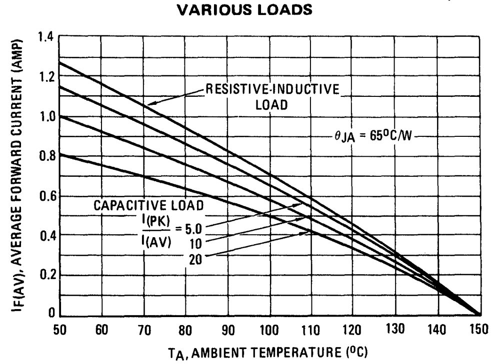


FIGURE 10 — PRINTED CIRCUIT BOARD MOUNTING, VARIOUS LOADS



SQUARE WAVE INPUT

FIGURE 7 — EFFECT OF LEAD LENGTHS, RESISTIVE LOAD

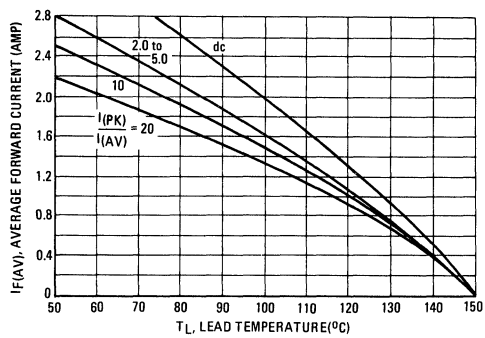


FIGURE 9 — 1/8" LEAD LENGTH, VARIOUS LOADS

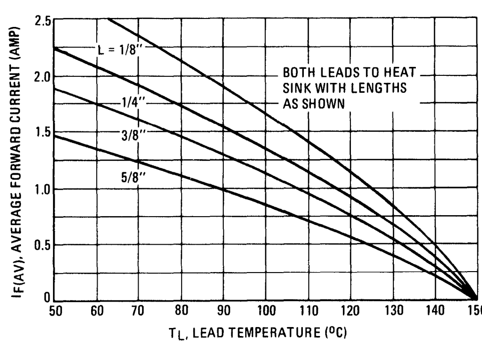


FIGURE 11 — PRINTED CIRCUIT BOARD MOUNTING, VARIOUS LOADS

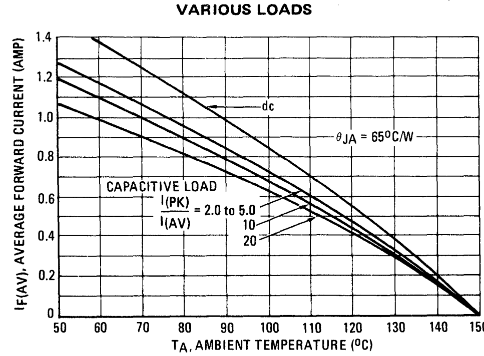


FIGURE 12 – THERMAL RESPONSE

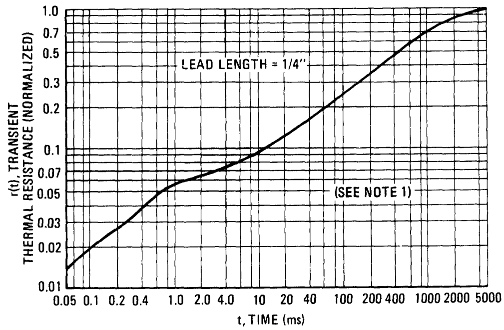
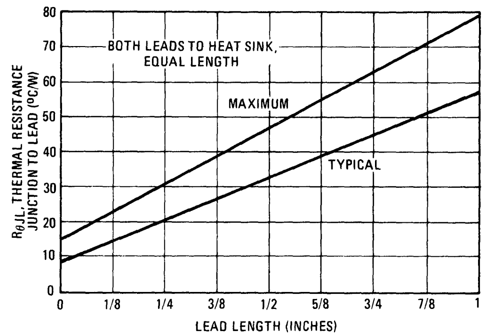
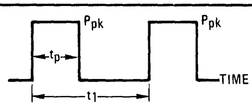


FIGURE 13 – THERMAL RESISTANCE



NOTE 1



DUTY CYCLE, $D = t_p/t_1$
PEAK POWER, P_{pk}, is peak of an equivalent square power pulse.

To determine maximum junction temperature of the diode in a given situation, the following procedure is recommended:

The temperature of the case should be measured using a thermocouple placed on the case as close as possible to the tie point. The thermal mass connected to the tie point is normally large enough so that it will not significantly respond to heat surges generated in the diode as a result of pulsed operation once steady-state conditions are achieved. Using the measured value of T_C, the junction temperature may be determined by:

$$T_J = T_C + \Delta T_{JC}$$

where ΔT_{JC} is the increase in junction temperature above the case temperature. It may be determined by:

$$\Delta T_{JC} = P_{pk} \cdot R_{\theta JC} \left[D + (1 - D) \cdot r(t_1 + t_p) + r(t_p) - r(t_1) \right]$$

where

$r(t)$ = normalized value of transient thermal resistance at time, t, from Figure 12, i.e.:

$r(t_1 + t_p)$ = normalized value of transient thermal resistance at time $t_1 + t_p$.

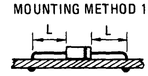
NOTE 2

Data shown for thermal resistance junction-to-ambient (θ_{JA}) for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

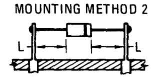
TYPICAL VALUES FOR θ_{JA} IN STILL AIR

MOUNTING METHOD	LEAD LENGTH, L (IN) 1/8	1/4	1/2	3/4	$R_{\theta JA}$
1	65	72	82	92	°C/W
2	74	81	91	101	°C/W
3		40			°C/W

MOUNTING METHOD 1



MOUNTING METHOD 2



Vector pin mounting

MOUNTING METHOD 3

P. C. Board with 1-1/2" x 1-1/2" copper surface

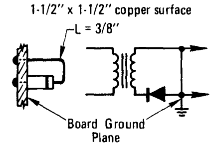
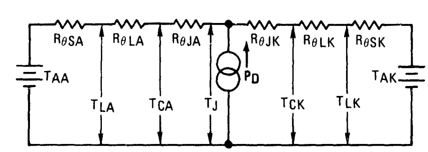


FIGURE 14 – THERMAL CIRCUIT MODEL



Use of the above model permits junction to lead thermal resistance for any mounting configuration to be found. For a given total lead length, lowest values occur when one side of the rectifier is brought as close as possible to the heat sink. Terms in the model signify:

T_A = Ambient Temperature
T_L = Lead Temperature
T_C = Case Temperature
T_J = Junction Temperature
$R_{\theta S}$ = Thermal Resistance, Heat Sink to Ambient
$R_{\theta L}$ = Thermal Resistance, Lead to Heat Sink
$R_{\theta J}$ = Thermal Resistance, Junction to Case
P_D = Power Dissipation

(Subscripts A and K refer to anode and cathode sides respectively.)

Values for thermal resistance components are:

$R_{\theta L}$ = 112°C/W/IN. Typically and 128°C/W/IN Maximum
$R_{\theta J}$ = 18°C/W Typically and 30°C/W Maximum

The maximum lead temperature may be calculated as follows:

$$T_L = 150° - \Delta T_{JL}$$

ΔT_{JL} can be calculated as shown in NOTE 1 or it may be approximated as follows:

$\Delta T_{JL} \approx R_{\theta JL} \bullet P_F$; P_F may be formulated for sine-wave operation from Figure 3 or from Figure 4 for square-wave operation.

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TYPICAL DYNAMIC CHARACTERISTICS

FIGURE 15 – FORWARD RECOVERY TIME

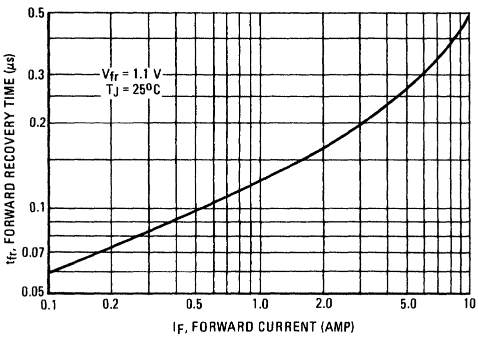
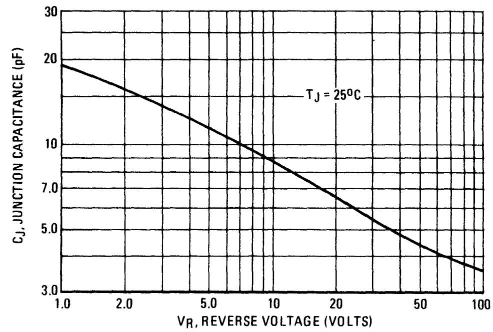


FIGURE 16 – JUNCTION CAPACITANCE



TYPICAL RECOVERED STORED CHARGE DATA

(SEE NOTE 3)

FIGURE 17 – T_J = 25°C

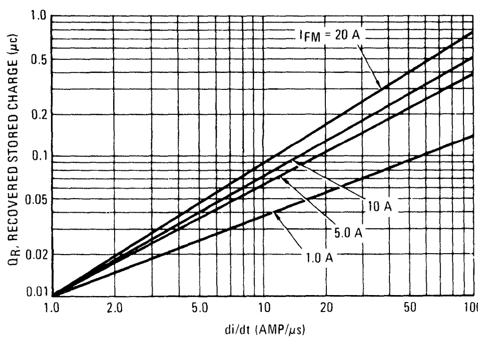


FIGURE 18 – T_J = 75°C

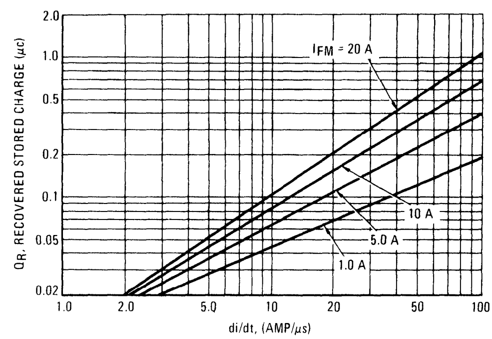


FIGURE 19 – T_J = 100°C

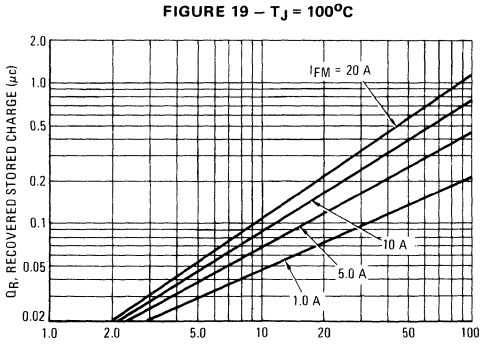


FIGURE 20 – T_J = 150°C

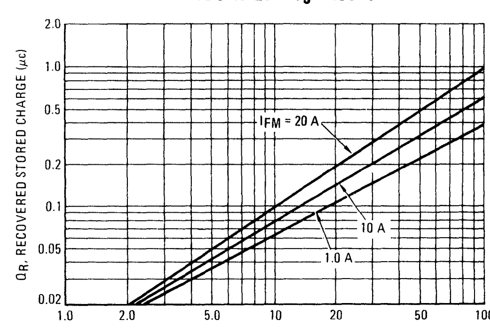


FIGURE 21 – REVERSE RECOVERY CIRCUIT

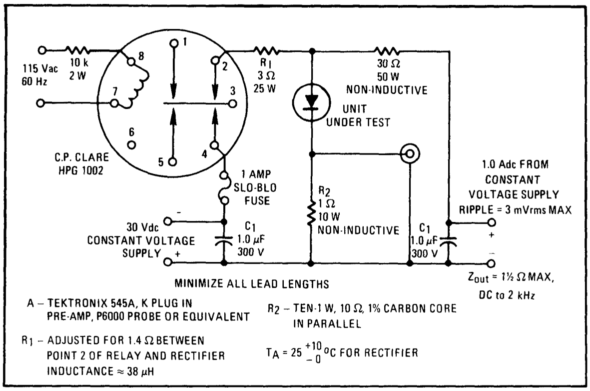
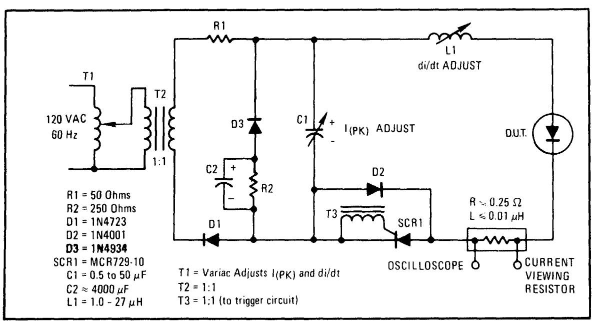


FIGURE 22 – JEDEC REVERSE RECOVERY CIRCUIT



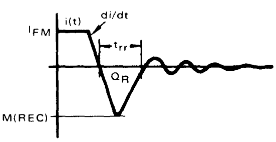
NOTE 3

Reverse recovery time is the period which elapses from the time that the current, thru a previously forward biased rectifier diode, passes thru zero going negatively until the reverse current recovers to a point which is less than 10% peak reverse current.

Reverse recovery time is a direct function of the forward current prior to the application of reverse voltage.

For any given rectifier, recovery time is very circuit dependent. Typical and maximum recovery time of all Motorola fast recovery power rectifiers are rated under a fixed set of conditions using I_F = 1.0 A, V_R = 30 V. In order to cover all circuit conditions, curves are given for typical recovered stored charge versus commutation di/dt for various levels of forward current and for junction temperatures of 25°C, 75°C, 100°C, and 150°C.

To use these curves, it is necessary to know the forward current level just before commutation, the circuit commutation di/dt, and the operating junction temperature. The reverse recovery test current waveform for all Motorola fast recovery rectifiers is shown.



From stored charge curves versus di/dt, recovery time (t_{rr}) and peak reverse recovery current ($I_{RM(REC)}$) can be closely approximated using the following formulas:

$$t_{rr} = 1.41 \times \left[\frac{Q_R}{di/dt}\right]^{1/2}$$

$$I_{RM(REC)} = 1.41 \times \left[Q_R \times di/dt\right]^{1/2}$$

FIGURE 23 – TYPICAL REVERSE LEAKAGE

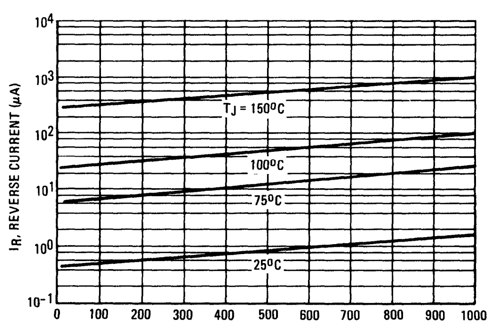


FIGURE 24 – TYPICAL REVERSE LEAKAGE